

# 2A,50-1000V Fast Recovery Rectifiers

#### **Features**

- Low leakage current
- Low forward voltage drop
- Glass passivated chip junction
- Moisture sensitivity: level 1, per J-STD-020
- Halogen-free according to IEC 61249-2-21 definition
- High temperature soldering guaranteed: 260°C/10 seconds



## **Applications**

For use of fast switching rectification in lighting, cellular phone, portable device, power supplies and other consumer applications.

| Maximum Ratings & Electrical Characteristics (TA=25°C unless otherwise noted)                         |                    |             |      |      |      |      |      |      |      |
|---|--------------------|-------------|------|------|------|------|------|------|------|
| Parameter   | Symbol             | L2F1        | L2F2 | L2F3 | L2F4 | L2F5 | L2F6 | L2F7 | Unit |
| Maximum repetitive peak<br>reverse voltage  | VRRM               | 50          | 100  | 200  | 400  | 600  | 800  | 1000 | V    |
| Maximum RMS voltage   | VRMS               | 35          | 70   | 140  | 280  | 420  | 560  | 700  | V    |
| Maximum DC blocking voltage   | V <sub>DC</sub>    | 50          | 100  | 200  | 400  | 600  | 800  | 1000 | V    |
| Maximum average forward rectified current   | I <sub>F(AV)</sub> | 2           |      |      | А    |      |      |      |      |
| Peak forward surge<br>current,8.3ms single half sine-<br>wave superimposed on rated<br>load per diode | I <sub>FSM</sub>   | 60          |      |      | A    |      |      |      |      |
| Operating junction<br>temperature range   | TJ                 | -55 to +150 |      |      | °C   |      |      |      |      |
| Storage temperature range   | T <sub>STG</sub>   | -55 to +150 |      |      | °C   |      |      |      |      |

| Thermal-Mechanical Specifications (TA=25°C unless otherwise noted) |                  |     |       |  |  |
|--|------------------|-----|-------|--|--|
| Parameter  | Symbol           | Тур | Unit  |  |  |
| Thermal Resistance, Junction to Ambient                            | R <sub>0JA</sub> | 85  | °C/W  |  |  |
| Thermal Resistance, Junction to Case                               | Rejc             | 15  | °C /W |  |  |
| Thermal Resistance, Junction to Lead                               | Rejl             | 18  | °C/W  |  |  |



| Electrical Specifications (TA=25°C unless otherwise noted) |        |  |        |      |      |      |      |      |      |      |
|--|--------|--|--------|------|------|------|------|------|------|------|
| Parameter  | Symbol | Test<br>Conditions   | L2F1   | L2F2 | L2F3 | L2F4 | L2F5 | L2F6 | L2F7 | Unit |
| Forward Drop<br>Voltage                                    | VF     | I⊧=2A  | 1.3    |      |      |      | V    |      |      |      |
| Reverse<br>leakage   | IR     | TJ =25℃  | 25°C 5 |      |      |      |      | uA   |      |      |
| current @V <sub>R</sub>                                    | IR     | T <sub>J</sub> =125°C  | 50     |      |      |      |      | uA   |      |      |
| Typical<br>junction<br>capacitance                         | CJ     | 4.0 V<br>1 MHZ   | 11     |      |      |      | pF   |      |      |      |
| Maximum<br>reverse<br>recovery time                        | trr    | I <sub>F</sub> =0.5A,<br>I <sub>R</sub> =1.0A,<br>I <sub>RR</sub> =0.25A |        | 1    | 50   |      | 250  | 50   | 00   | nS   |

Note:

1. Mounted on copper pad area of 0.2x0.2" (5.0 x 5.0mm) to each terminal.



### **Ratings and Characteristics Curves**







Figure 3. Typical Reverse Characteristics



Figure 5. Typical Junction Capacitance



Characteristics



## Package Outline Dimensions

in inches (millimeters)

## eSGB (DO-221AC)

A1





| DIM | Unit: | mm   | Unit: inch |       |  |
|-----|-------|------|------------|-------|--|
|     | MIN   | MAX  | MIN        | MAX   |  |
| А   | 0.92  | 1.08 | 0.036      | 0.043 |  |
| A1  | 0     | 0.1  | 0.000      | 0.004 |  |
| В   | 1.25  | 1.45 | 0.049      | 0.057 |  |
| С   | 0.1   | 0.25 | 0.004      | 0.010 |  |
| D   | 2.6   | 2.8  | 0.102      | 0.110 |  |
| Е   | 4.1   | 4.3  | 0.161      | 0.169 |  |
| L   | 0.7   | 1.1  | 0.028      | 0.043 |  |
| HE  | 4.8   | 5.2  | 0.189      | 0.205 |  |

Soldering footprint



## **Revision History**

| Document Version | Date of release | Description of changes |
|------------------|-----------------|------------------------|
| Rev.A            | 2021.06.01      | Released Datasheet     |
| Rev.B            | 2023.10.12      | Modify document format |
| Rev.C            | 2023.12.29      | Modify package name    |



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